APPLICABLE STANDARD

ELECTRIC CHARACTERISTICS				-35 °C TO +85°C (NOTE1)			TEMPERATURE RAI			-10 °C TO +60°C (NOTE3)			
APPLICABLE DF61-2S-2.2C	RATING			20% TO 80% (NOTE2)				ANGE		40% TO 70% (No		OTE3)	
SPECIFICATIONS TEM		APPLICABLE		DF61-2S-2.2C				IT ^					
SPECIFICATIONS TEST METHOD REQUIREMENTS OT AT CONSTRUCTION GENERAL EXAMINATION (VISUALLY AND BY MEASURING INSTRUMENT. GENERAL EXAMINATION (VISUALLY AND BY MEASURING INSTRUMENT.) GENERAL INSTRUMENT IN THE AND BY MEASURING INSTRUMENT. GENERAL EXAMINATION (VISUALLY AND BY MEASURING INSTRUMENT.) GENERAL TO CONTACT INSTRUMENT. GENERAL EXAMINATION (VISUALLY EXAMINATION FOR INSTRUMENT.) GENERAL EXAMINATION (VISUALLY EXAMINATION FOR INSTRUMENT.) GENERAL INSTRUMENT IN THE AND BY MEASURING INSTRUMENT. GENERAL INSTRUMENT INSTRUMENT IN THE AND BY MEASURING INSTRUMENT. GENERAL INSTRUMENT IN THE AND BY MEASURING INSTRUMENT IN THE AND BY MEASURING INSTRUMENT. GENERAL INSTRUMENT IN THE AND BY MEASURING IN THE AND BY MEASURING INSTRUMENT IN THE AND BY MEASURIN				350 V AC/DC									
TITEM TEST METHOD REQUIREMENTS QT AT CONSTRUCTION GENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. GENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. GENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. GENERAL EXAMINATION OF CONTRIBED VISUALLY. ELECTRIC CHARACTERISTICS ONLY OF TERRISTANCE. GIVEN MAX. THA (OF 0 1000Hz). 10 mg MAX. VISUALIZATION FOR SETANCE. VISUALIZ				SPEC	IFICA	OITA	NS						
SENERAL EXAMINATION VISUALLY AND BY MEASURING INSTRUMENT. ACCORDING TO DRAWING. X X X X X X X X X	l-	TEM						R	EQU	IREMENTS	QT	АТ	
MARKING CONFIRMED VISUALLY. X X X X X X X X X			N N				I .						
CONTACT RESISTANCE 20mm MAX_ IMA (DIC or 1000Hz) 10 ms MAX	GENERAL E	EXAMIN	ATION VISUALL	VISUALLY AND BY MEASURING INSTRUMENT.				ACCORDING TO DRAWING. X X					
CONTROL RESISTANCE 00 V DC	MARKING		CONFIR	CONFIRMED VISUALLY.							Х	Х	
MILLIOUT LEVEL METHOD				STICS									
WECHANICAL CHARACTERISTICS MECHANICAL 30 TIMES INSERTION AND EXTRACTION 2NO FLASHOVER OR BREAKDOWN. X → CONTACT RESISTANCE 20 m Ω MAX. 2NO DAMAGE, CRACK OR LOOSENESS OF PARTS ON THE STAND EXTRACTION 1T TAKES OUT AND INSERTS WITH A CONFORMITY 2NO DAMAGE, CRACK OR LOOSENESS OF PARTS ON FRECUENCY 1070 55 Hz, SINGLE AMPLITUDE 1070 MIN. X → CONTACT INSERTION AND EXTRACTION FORCE : 20 M MAX. 3NO DAMAGE, CRACK OR LOOSENESS OF PARTS OF SINGLE AMPLITUDE 2NO DAMAGE, CRACK OR LOOSENESS OF P			20111 0 1017 (20mV MAX, 1mA (DC or 1000Hz).				10 mΩ MAX.				-	
MECHANICAL CHARACTERISTICS MECHANICAL OPERATION SO TIMES INISESTION AND EXTRACTION. CONTACT INSERTION OPERATION THE ALEXES OUT AND INSERTS WITH A CONFORMITY CONTACT INSERTION OF FECURITY 10 TO 55 Hz, SINGLE AMPLITUDE OF THE ALEXES OUT AND INSERTS WITH A CONFORMITY CONTACT INSERTION OF THE ALEXES OUT AND INSERTS WITH A CONFORMITY CONTACT INSERTION OF THE ALEXES OUT AND INSERTS WITH A CONFORMITY CONTACT INSERTION OF THE ALEXES OUT AND INSERTS WITH A CONFORMITY CONTACT INSERTION OF THE ALEXES OUT AND INSERTS WITH A CONFORMITY CONTACT INSERTION FORCE: 20 NM MAX X — CONTACT RESISTANCE: 20 NM MAX X — CONTACT RESISTANCE: 20 NM MAX CONTACT RESISTANCE: 20 NM MA	INSULATION RESISTANCE		ANCE 500 V DC	500 V DC.				1000 MΩ MIN.				-	
MECHANICAL 30 TIMES INSERTION AND EXTRACTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION TTAKES OUT AND INSERTS WITH A CONFORMITY 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION TTAKES OUT AND INSERTS WITH A CONFORMITY 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION TTAKES OUT AND INSERTS WITH A CONFORMITY 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 2000 DAMAGE, CRACK OR LOOSENESS OF PARTS. X CONTRACT INSERTION 20	VOLTAGE PROOF		1700 V A	1700 V AC FOR 1 min.				NO FLASHOVER OR BREAKDOWN.				_	
OPERATION													
CONTACT INSERTION	1		30 TIMES	30 TIMES INSERTION AND EXTRACTION.				12				-	
AND EXTRACTION FORCES CONNECTOR CAPITAL TO RECIDENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 10 CYCLES FOR 3 DIRECTION CAPITAL CAPITAL DIRECTIONS CAPITAL CAPITA			ON IT TAKES	IT TAKES OUT AND INSERTS WITH A CONFORMITY								 -	
0.75 mm, AT 10 CYCLES FOR 3 DIRECTION. 20 No DAMAGE, CRACK OR LOOSENESS OF PARTS. 1													
SPOCK	VIRKATION											-	
ENVIRONMENTAL CHARACTERISTICS DAMP HEAT (STEADY STATE) (STE	SHOCK		490 m/s ² [490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3				DAWAGE, GRACK OR LOUGENESS OF PARTS.				-	
DAMP HEAT EXPOSED AT 40 ± 2°, 90 TO 95 %, 96 h (AFTER LEAVING THE ROOM TEMPERATURE FOR 1-2h.) (AFTER LEAVING THE ROOM TEMPERATURE FOR 1-2h.) (AFTER LEAVING THE ROOM TEMPERATURE FOR 1-2h.) (3)NO DAMAGE, CRACK OR LOOSENESS OF PARTS TEMPERATURE (1)		IN/ENI											
(AFTER LEAVING THE ROOM TEMPERATURE FOR 1/2 h.) RAPID CHANGE OF TEMPERATURE -55°C→ +85°C TEMPERATURE TIME 30min→30min UNDER S CYCLES (THE TRANSFERRING TIME OF THE TANK IS 2~3 min) (AFTER LEAVING THE ROOM TEMPERATURE FOR 1~2h.) RESISTANCE TO SOLDERING HEAT TIME 1 merel 20 min 2 merel 2		NIVILIN						①CONTACT RESISTANCE: 20 mQ MAX X					
RAPID CHANGE OF TIME 30min- 30min UNDER 5 CYCLES (THE TRANSFERRING TIME 07 THE TANK IS 2~3 min) (AFTER LEAVING THE ROOM TEMPERATURE FOR 1~21) (AFTER LOW TIME) (AFTER LOW TI	(STEADY STA	ATE)	1,	`				I 🗔					
TEMPERATURE TIME 30min	DADID CHAN	ICE OE	· · · · · · · · · · · · · · · · · · ·	´				- "					
(THE TRANSFERRING TIME OF THE TANK IS 2~3 min) (AFTER LEAVING THE ROOM TEMPERATURE FOR 1~2m) RESISTANCE TO SOLDERING HEAT 1 REFLOW SOLDERING «REFLOW TIME» NUMBER OF REFLOW CYCLES: 2 CYCLES MAX. DURATION ABOVE 220 °C, 60 sec. MAX. PEAK TEMPERATURE: 250°C 10 sec. MAX. PPE-HEAT TIME (MAX): 130 °C PRE-HEAT TIME (MAX): 120 sec. 2) MANUAL SOLDERING SOLDERING RON TEMPERATURE: 350±10°C, SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION TEMPERATURE: 245°C DURATION OF IMMERSION TEMPERATURE: 350±10°C, SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF SW OF THE SURFACE BEING IMMERSED. ***OFTIME TEMPERATURE RISING BY CURRENT. **OFTIME TEMPERATURE AND HOMIDITY RANCE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. ***OFTIME TEMPERATURE AND HOMIDITY RANCE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. ***OFTIME TEMPERATURE AND HOMIDITY RANCE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. ***OFTIME TEMPERATURE AND HOMIDITY RANCE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. ***OFTIME TEMPERATURE AND HOMIDITY RANCE IS APPLIED								~					
RESISTANCE TO SOLDERING HEAT 1 REFLOW SOLDERING REFLOW SOLDERING REFLOW SOLDERING REFLOW SOLDERING REFLOW SOLDERING REFLOW SOLDERING REFLOW OYOLES: 2 CYCLES MAX. DURATION ABOVE 220 °C, 60 sec. MAX. PEAK TEMPERATURE: 260°C 10 sec. MAX. PEAK TEMPERATURE (MIN): 150 °C PRE-HEAT TIME (MIN): 150 °C PRE-HEAT TIME (MIN): 150 °C PRE-HEAT TIME (MIN): 120 sec. 2) MANUAL SOLDERING SOLDERING RON TEMPERATURE: 235°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. BOUTH OF THE SURFACE BEING IMMERSED. NO STRENGTH ON CONTACT: NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2NO CONDENSING NOTE3 PEPPERATURE RISING BY CURRENT. NOTE2NO CONDENSING NOTE3 PEPPERATURE RISING BY CURRENT. NOTE3 PEPPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. DESCRIPTION OF REVISIONS DESIGNED COUNT DESCRIPTION OF REVISIONS DESIGNED COUNT DESCRIPTION OF REVISIONS DESIGNED THE COUNT DESCRIPTION OF REVISIONS DESIGNED COUNT DESCRIPTION OF REVISIONS DESIGNED APPROVED KI, AKIYAMA 12, 04, 25 CHECKED HK, UMEHARA 13, 04, 05 REMARKS SPECIFICATION SHEET PART NO. DF61-2P-2. 2V (22)													
SOLDERING HEAT WREFLOW TIME> NUMBER OF REFLOW CYCLES: 2 CYCLES MAX. DURATION ABOVE 220 °C, 60 sec. MAX. PFAK TEMPERATURE: 250°C 10 sec. MAX. PFAK TEMPERATURE: 250°C 10 sec. MAX. PFAK TEMPERATURE: 250°C 10 sec. MAX. PFAK-HEAT TIME> PRE-HEAT TIME> PRE-HEAT TIME NOWN: 150 °C PRE-HEAT TIME NOWN: 120 sec. 2) MANUAL SOLDERING SOLDERING SOLDERING Sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. POURATION OF IMMERSION: SOLDERING FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE RAND HUMIDITY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 24 DESIGNED TI. OHSAKO 12. 04. 24 DESIGNED TI. OHSAKO 12. 04. 24 DESIGNED TI. OHSAKO 12. 04. 24 DRAWN TI. OHSAKO 12. 04. 24			,	,									
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX. DURATION ABOVE 220 °C, 60 sec. MAX. PEAK TEMPERATURE: 250°C 10 sec. MAX. «PRE-HEAT TIME: 250°C 10 sec. MAX. «PRE-HEAT TIME (MIN): 150 °C PRE-HEAT TIME (MIN): 90 sec. PRE-HEAT TIME (MIN): 90 sec. PRE-HEAT TIME (MIN): 90 sec. 2) MANUAL SOLDERING IRON TEMPERATURE: 350±10°C, SOLDERING IRON TEMPERATURE: 345°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. BEING IMMERSED. NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2: NO CONDENSING NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS UNITES SPECIFICATION SHEET DRAWING NO. ELC4-336115-02 PART NO. DF61-2P-2. 2V (22)			'	,								_	
PEAK TEMPERATURE: 250°C 10 sec. MAX. «PRE-HEAT TIME» PRE-HEAT TEMPERATURE (MIN): 150°C PRE-HEAT TIME (MIN): 150°C PRE-HEAT TIME (MIN): 120 sec. 2) MANUAL SOLDERING SOLDERING ISON TEMPERATURE: 350±10°C, SOLDERING TIME: 3sec. NO STRENSTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. NO STRENSTH ON CONTACT. NOTE: 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE: 2000 CONDENSING NOTE: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED THE CONDENSIONS I DIS-H-007811 ST. SATO HK. UMEHARA 13.04.05 APPROVED KI. AKI IYAMM 12.04.25 CHECKED HK. UMEHARA 12.04.24 DESIGNED TH. OHSAKO 12.04.24 DRAWN TT. OHSAKO 12.04.24 DRAWN TT. OHSAKO 12.04.24 DRAWN TT. OHSAKO 12.04.24 PART NO. DF61-2P-2. 2V (22)	SOLDERING	HEAI		NUMBER OF REFLOW CYCLES: 2 CYCLES MAX. DURATION ABOVE 220 °C, 60 sec. MAX. PEAK TEMPERATURE: 250°C 10 sec. MAX. «PRE-HEAT TIME» PRE-HEAT TEMPERATURE(MIN):150 °C PRE-HEAT TEMPERATURE(MAX):180 °C									
RPRE-HEAT TIME PRE-HEAT TIME (MIN)::150 °C PRE-HEAT TIME (MIN)::150 °C PRE-HEAT TIME (MIN)::90 sec. PRE													
PRE-HEAT TEMPERATURE (MIN): 150 °C PRE-HEAT TIME (MIN): 180 °C PRE-HEAT TIME (MIN): 190 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE: 350±10°C, SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. NOTE3: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2: NO CONDENSING NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 NOTE QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-336115-02													
PRE-HEAT TIME (MIN): 90 sec. PRE-HEAT TIME (MAX): 120 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE: 350±10°C, SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2: NO CONDENSING NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DE													
PRE-HEAT TIME (MAX) : 120 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350±10°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE : 245°C DURATION OF IMMERSION : SOLDERING, FOR 5 sec. DURATION OF IMMERSION : SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED. NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2: NO CONDENSING NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE APPROVED K1. AKIYAMA 13. 04. 05 CHECKED HK. UMEHARA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. OHSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 0													
SOLDERING IRON TEMPERATURE :350±10°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE : 245°C DURATION OF IMMERSION :SOLDERING, FOR 5 sec. DURATION OF IMMERSION :SOLDERING, FOR 5 sec. NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:NO CONDENSING NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK, UMEHARA 13, 04, 05 REMARKS APPROVED KI. AKIYAMA 12, 04, 25 CHECKED HK, UMEHARA 12, 04, 24 DESIGNED TT. OHSAKO 12, 04, 24 DRAWN TT. OHSAKO 12, 04, 24 DRAWING NO. SPECIFICATION SHEET PART NO. DF61-2P-2. 2V (22)													
SOLDERING TIME: 3sec. NO STRENGTH ON CONTACT. SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE 2: NO CONDENSING NOTE 3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 DRAWING NO. ELC4-336115-02			'	2) MANUAL SOLDERING									
SOLDERABILITY SOLDERING TEMPERATURE: 245°C DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. DURATION OF IMMERSION: SOLDERING, FOR 5 sec. NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2:NO CONDENSING NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD, OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED HK. UMEHARA 13. 04. 05 CHECKED HK. UMEHARA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO DRAWN TT. 0HSAKO TT. 0HSAKO					350±10℃,								
DURATION OF IMMERSION : SOLDERING, FOR 5 sec. COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED. NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2: NO CONDENSING NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. 0HSAKO 13. 04. 05 DESIGNED TT. 0HSAKO 13. 04. 05 DESIGNED TT. 0HSAKO 13.													
NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT. NOTE2: NO CONDENSING NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SAT0 HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-336115-02 PART NO. DF61-2P-2. 2V (22)	SOLDERABILITY						COVER MINIMUM OF 95 % OF THE SURFACE				X	-	
NOTES: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD, AFTER PCB BOARD OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION. COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE 1 DIS-H-007811 ST. SATO HK. UMEHARA 13. 04. 05 REMARKS APPROVED KI. AKIYAMA 12. 04. 25 CHECKED HK. UMEHARA 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DESIGNED TT. 0HSAKO 12. 04. 24 DRAWN TT. 0HSAKO 12. 04. 24 Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. DF61-2P-2. 2V (22)				RISING BY CURRENT.			1				1	1	
COUNT DESCRIPTION OF REVISIONS DESIGNED CHECKED DATE				OF LONG TERM STORAGE	FOR UNL	JSED PF	RODUCT	S BEFOR	PCB	ON BOARD, AFTER P	св во	ARD ,	
1			EMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTER										
APPROVED K1. AKIYAMA 12. 04. 25	COUN	NT											
Unless otherwise specified, refer to JIS C 5402. CHECKED	REMARKS		וע	⊃=H=UU/01 I		31.5	DATU	APPRO	ven l		 		
Unless otherwise specified, refer to JIS C 5402. DRAWN											-		
Note QT:Qualification Test AT:Assurance Test X:Applicable Test DRAWING NO. ELC4-336115-02 PART NO. DF61-2P-2. 2V (22)	Linioss of	envice	enacified refer	ied, refer to JIS C 5402.				DESIGN	1ED	TT. OHSAKO	12.0	04. 24	
SPECIFICATION SHEET PART NO. DF61-2P-2. 2V (22)	OTHESS OUT	ei wise	specified, refer					DRAW	/N	TT. OHSAKO	12.0)4. 24	
AG SEEM IS ATTENDED IN	Note QT:Qualification Test AT:Assurance Test X:Applicable Test				est	DRAW		/ING NO. ELC4-336115-02					
	HRS		SPECIFI	PECIFICATION SHEET			ΓNO.		DF61-2P-2. 2V (22)				
FORM HD0011-2-1			HIROSE E	LECTRIC CO., LTD.		CODE	E NO.	CL	666	-5001-1-22	Δ	1/1	